Final Product/Process Change Notification

Document #:FPCN25566X
Issue Date:26 Sep 2023

Title of Change:	Transfer of Assembly and Test operations of the selected TO3PF IGBT parts, outsource from onsemi Suzhou to Good-Ark China
Proposed First Ship date:	31 Dec 2023 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or TieJun.Ding@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Harper.Pan@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	The traceability of marking will be maintained by assembly plant code, lot code and date code
Change Category:	Assembly Change, Test Change
Change Sub-Category(s):	Manufacturing Site Transfer, Material Change

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
None	Good-Ark, China

Description and Purpose:

This FPCN is to inform customers of the transfer of TO3PF IGBT products to new assembly and test site Good-Ark, China.

For assembly changes:

	From	**To**
Assembly & Final Test Sites	Onsemi Suzhou	Good-Ark,China
Die Attach	PB93.5SN5AG1.5	PB92.5SN5AG2.5

	From	**To**
Product marking change	Existing Line 1: Internal traceability Line 2 & Line 3: device marking	Corporate marking style Line 1 & Line 2: device marking Line 3: Internal traceability (AYWWZZ)

Reliability Data Summary:

QV DEVICE NAME: FGAF40N60SMD
PACKAGE: TO-3PF
RMS: U86807

Test	Specification	Condition	Interval	Result
High Temperature Reverse Bias	JESD22-A108	Ta=175°C, 80% max rated V	1008 hrs	0/77
High Temperature Gate Bias	JESD22-A108	Ta=175°C, 100% max rated Vgss	1008 hrs	0/77
High Temperature Storage Life	JESD22-A103	Ta=175°C	1008 hrs	0/77
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/77
High Humidity High Temperature Reverse Bias Test	JESD22-A101	85°C, 85% RH, 18.8psig, bias	96 hrs	0/77
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/77
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only	end points	0/30
Solderability	JSTD002	Ta = 245°C, 5 sec	end points	0/15
Lead integrity	JESD22-B105	Lead Tension test for 10pcs units. Lead Bending test for 10pcs units. Lead Fatigue test for 10pcs units.	end points	0/30

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

Part Number	Qualification Vehicle
FGAF40N60SMD	FGAF40N60SMD
FGAF40N60UFTU	FGAF40N60SMD

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Appendix A: Changed Products

PCN#: FPCN25566X
Issue Date: Sep 25, 2023

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
FGAF40N60SMD		FGAF40N60SMD	NA	
FGAF40N60UFTU		FGAF40N60SMD	NA	